

MATE ★ U11 88-200202/29 ★ J6 3135-452-A
Resin material for sealing semiconductor plastics packages -
comprises silica flake filler and thermosetting or thermoplastic
resin

MATSUSHITA ELTRN CORP 26.11.86-JP-282414

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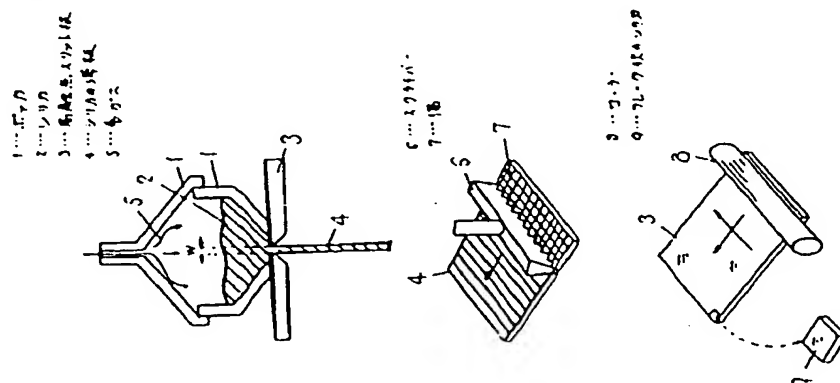
Sealing resin material contains as a filler silica flakes mixed with a thermosetting resin or thermoplastic resin. Specifically the silica flakes each have size of 100 microns or smaller thickness and 10 x 10 microns - 1000 x 1000 micron in length x width.

USE/ADVANTAGE - For resin material to seal plastic packages where semiconductors are mounted. When light strikes the surface of the resin material in particular direction, less refraction and diffusion of the light is generated. This enables translucent boards for sealing to be moulded.

In an example silica was melted, and passed through an alumina slit plate at 1500 deg.C or higher to form a silica thin sheet. The silica thin sheet was scribed in a lattice form, and pressed with a hard roller. The resultant silica flakes were mixed with epoxy resin, excluding conventional carbon black as a light shielding material. The silica flakes were oriented during melt-flowing and in the moulding. (3pp Dwg.No.1-3/3)

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128, Theobalds Road, London WC1X 8RP, England

US Office: Derwent Inc.

Suite 500, 6845 Elm St. McLean, VA 22101

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